



High speed imaging for dynamic testing of materials and structures

21st DYMAT Technical Meeting

18–20 November 2013, Institute of Physics, London, UK

Organised jointly by the IOP Applied Physics and Technology Division and DYMAT Association



<http://aptd.iopconfs.org>

Main conference themes

- Metrology
 - Camera/equipment assessment
 - DIC, grids, etc: metrological evaluation for full-field strain and acceleration measurements
 - High and ultra high speed full-field thermal measurements
- Methodology
 - Full-field measurements data processing
 - Parameter identification/inverse problems
 - Innovative test design
- Applications
 - Constitutive behaviour
 - Failure/fracture
 - Observation of damage and failure processes
 - All types of materials/structures will be considered

Keynote speakers

- Prof. John E Field, University of Cambridge, UK
- Dr Phillip Reu, Sandia National Laboratories, USA
- Prof. Mikael Sjödaahl, Luleå University of Technology, Sweden

Format

The meeting will take place over three days in single-session format to maximise interaction between speakers and audience. The conference will also include interactive poster sessions, an exhibition of high-speed camera manufacturers and a round-table session on current challenges and future developments in high-speed imaging.

Publication

Four-page abstracts for oral and poster presentations are invited. In parallel, some authors will be asked to contribute to a themed issue on the meeting topic, to be published in *Strain* (Wiley-Blackwell).

Important deadlines

Extended abstract submission deadline	14 June 2013
Early registration deadline	31 July 2013
Registration deadline	11 November 2013

Organising committee

- Prof. Fabrice Pierron, University of Southampton, UK
- Prof. Janice M Barton, University of Southampton, UK
- Prof. Pascal Forquin, Lorraine University, France
- Dr Alec Goodyear, The Open University, UK
- Prof. William G Proud, Imperial College London, UK
- Dr Clive Siviour, University of Oxford, UK

Co-sponsors

British Society for Strain Measurement (BSSM); European Physical Society; the Imaging Science Group, Royal Photographic Society; Institute of Measurement and Control; Institution of Mechanical Engineers; Society for Experimental Mechanics, Inc (SEM)

Further information

<http://aptd.iopconfs.org>
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